

10

9

8

7

6

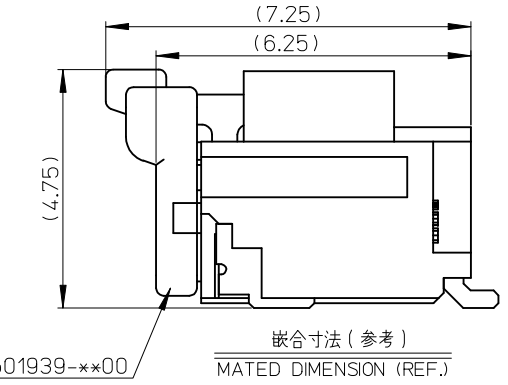
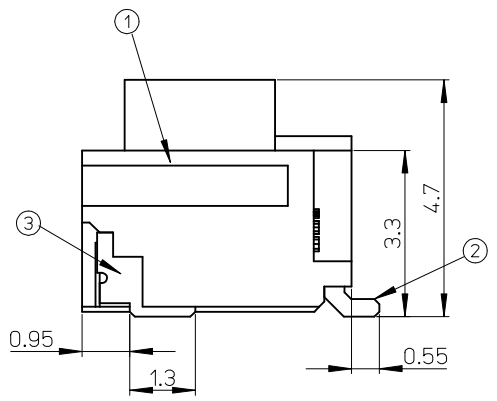
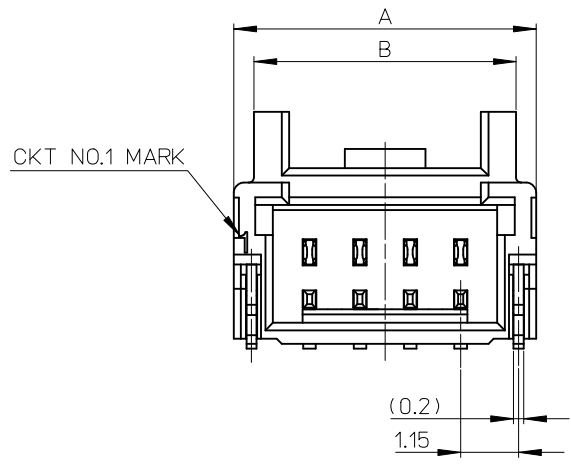
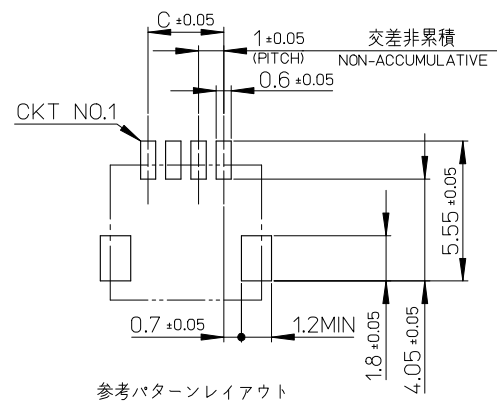
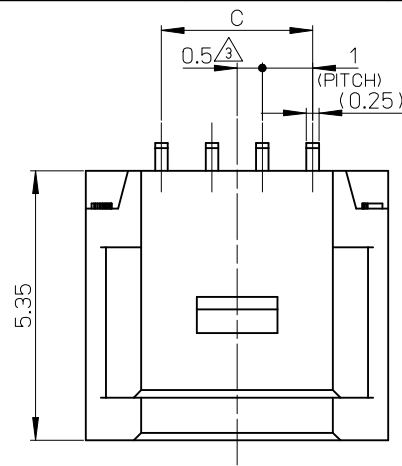
5

4

3

2

1



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)

NOTES.

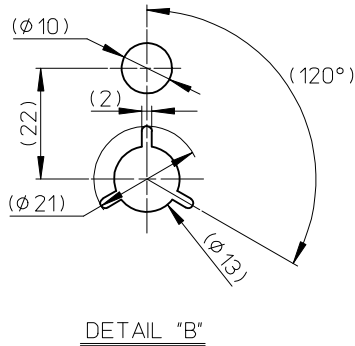
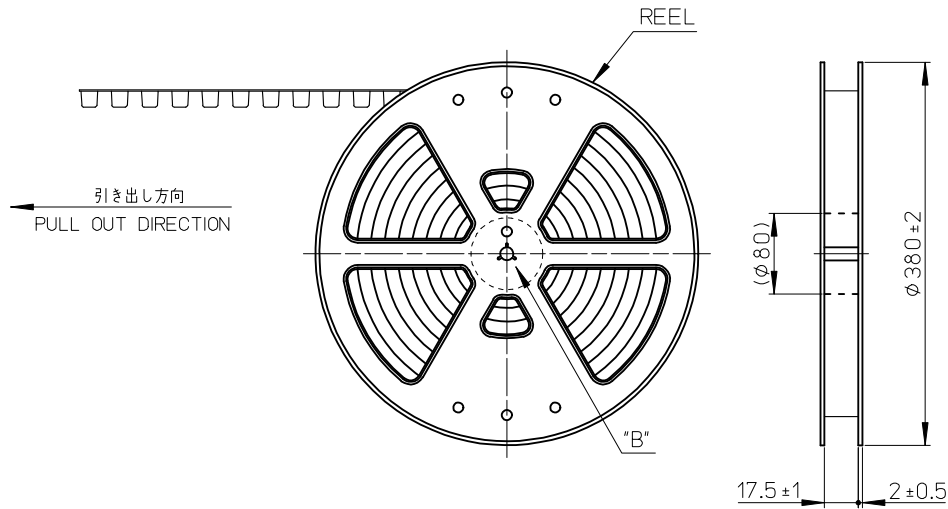
1. 嵌合相手: 501939-\*\*\*\*  
MATE WITH: 501939-\*\*\*\*
2. ソルダーピン及びネイル平坦度は、0.1MAX.  
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用  
APPLY FOR CKT SIZE=EVEN
- 4.ELV AND RoHS COMPLIANT.

4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	±0.25	NYOSHIDA	2005/09/16	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK					
	30 OVER	±0.3	CHECKED BY	DATE						
	ANGULAR	±3 °	AMIZUMURA	2005/09/16						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MOLEX INCORPORATED		DOCUMENT NO.		SHEET NO.		
		MYAGI	2005/09/16	SEE SHEET 2		SD-501953-001		1 OF 2		
		MATERIAL NO.								
		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

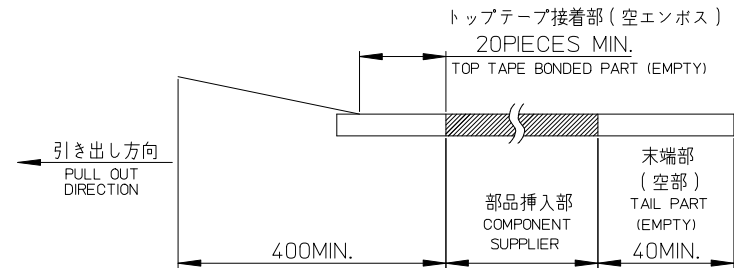
紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR	
501953-0597	501953-0587	501953-0577	501953-0567	5	
501953-0497	501953-0487	501953-0477	501953-0467	4	
501953-0397	501953-0387	501953-0377	501953-0367	3	
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数	
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS	
CONNECTOR SERIES No. 501953-***9					
青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 501953-***9					

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±---	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK  MOLEX INCORPORATED			
	10 OVER 30 UNDER	±---	CHECKED BY AMIZUMURA	DATE 2005/09/16				
	30 OVER	±---	APPROVED BY MYAGI	DATE 2005/09/16				
ANGULAR ±--- °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501953-001		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



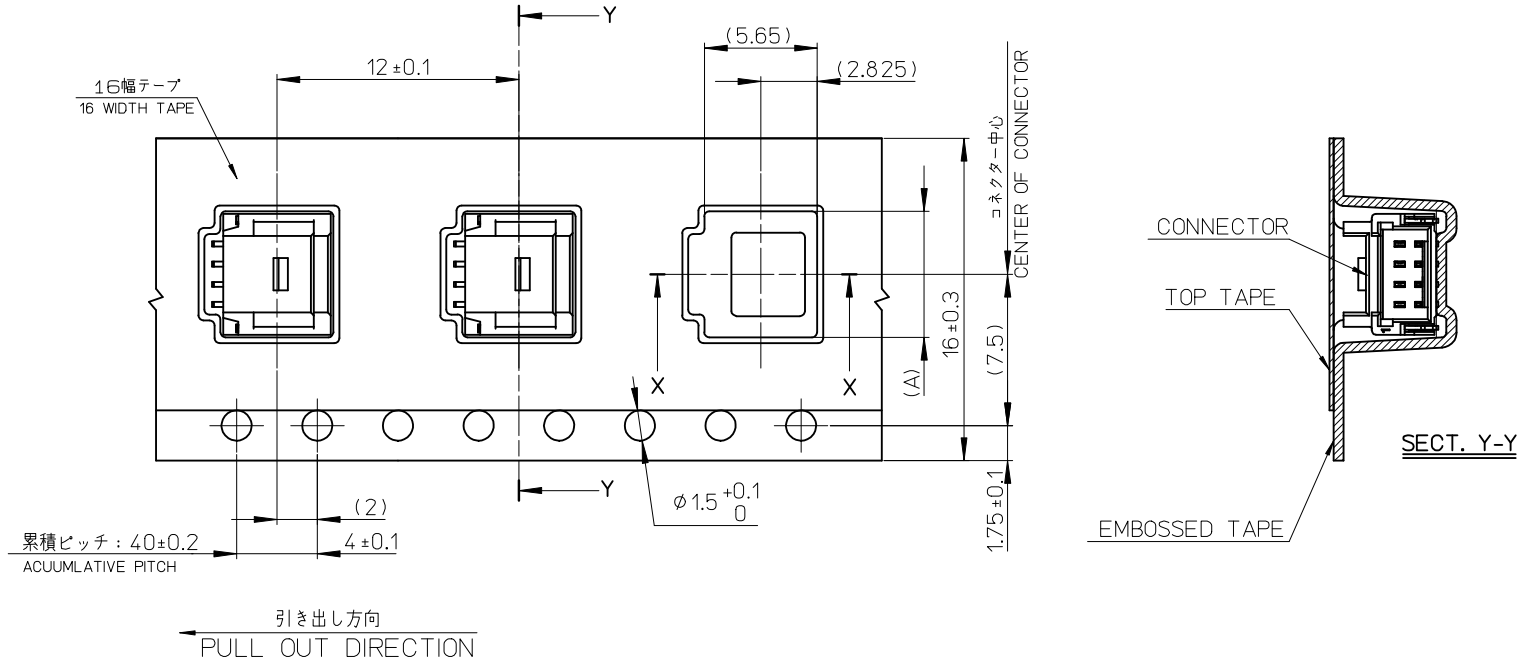
NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。  
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300個/リール  
NUMBER OF CONNECTORS: 1300PIECES/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



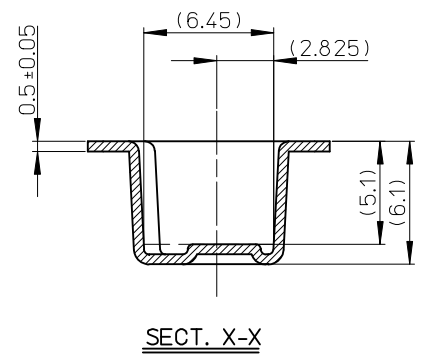
- 材料  
MATERIAL  
キャリアテープ: ポリスチレン  
CARRIER TAPE: POLYSTYRENE  
トップテープ: PET、その他  
TOP TAPE: PET, OTHER  
リール: ポリスチレン<リサイクル材を含む>  
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
- ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-\*\*07除く)  
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)  
(BESIDES 501953-\*\*07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501940-001参照)  
REFER TO PS-501940-001(HIGH BARRIER PRODUCT)  
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG	
	10 OVER 30 UNDER	±0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16	MATERIAL NO. SEE SHEET 3	DOCUMENT NO. SD-501953-002
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



累積ピッチ: 40±0.2  
ACUUMLATIVE PITCH

引き出し方向  
PULL OUT DIRECTION



SECT. X-X

7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG	
	10 OVER 30 UNDER	±0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16	DOCUMENT NO. SD-501953-002	SHEET NO. 2 OF 3
	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

CONFIDENTIAL

紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
501953-0597	501953-0587	501953-0577	501953-0567	5
501953-0497	501953-0487	501953-0477	501953-0467	4
501953-0397	501953-0387	501953-0377	501953-0367	3
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±---	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG			
		10 OVER 30 UNDER	±---	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED			
		30 OVER	±---	APPROVED BY MYAGI	DATE 2005/09/16	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501953-002	SHEET NO. 3 OF 3
REV		ANGULAR ±--- °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							